



## **PROCESS CHANGE NOTICE PCN0310**

### **MOLD COMPOUND CHANGE FOR 100 LEAD QFP PACKAGE**

#### **Change Description:**

ASE Malaysia will be extending the use of Nitto's MP-8000 series mold compound to Altera's 100 lead Quad Flat Package. Currently this package is using Sumitomo's EME-6300 series compound. The Nitto MP-8000 series compound has been successfully used on other lead counts in QFP and PLCC packages. The MP-8000 series mold compound has been fully qualified through Altera's Reliability Qualification program. This change will not affect any dimension or moisture rating performance aspects.

#### **Reason for Change:**

Apart from providing standardization of mold compound within all QFP packages, the MP-8000 series mold compound provides improved assembly yield and performance.

#### **Products Affected:**

All Altera® MAX® 7000 series products assembled in the 100 lead QFP package with the country of origin "Malaysia" will be affected by this change.

#### **Product Traceability and Transition Dates:**

This change will be implemented beginning December 2003. Beginning with the top mark date code of 0349, customers may receive the ASE QFP 100 package with the new mold compound. Altera's trace code marking can be decoded for material traceability.

#### **Contact:**

For more information, please contact your local Altera sales representative or the Altera Customer Quality Engineering Department.